semiconductor packaging news

EV Group Solutions for Heterogeneous Integration to be Highlighted at ECTC 2023 – May 23, 2023

semiconductor packaging news

We search for industry news, so you don't need to.

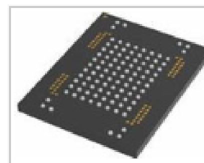
How to Tweezer Pull
Learn how to perform an optimal Pull/Peel test using Tweezers. This guide covers test method settings and failures modes for Tweezer Pull/Peel testing. Download it now.

xyztec

May 22, 2023

China Imposes Sales Restrictions on Micron

China has banned US chip maker Micron from selling to Chinese companies working on key infrastructure projects, in a major escalation of an ongoing battle between the world's top two economies over access to crucial technology. The Cyberspace Administration of China (CAC) announced the decision on Sunday, saying the US chip maker had failed to pass a cybersecurity review. The news came ...



CNN

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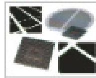
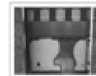

AI Technology, Inc.

Transform Your Sample Prep with LaserFIB
Rapidly access deeply buried features with precise targeting. Get site-specific cross- section results in minutes to hours. How? Watch our webinar.

ZEISS Microscopy

Meta pulls the curtain back on its A.I. chips for the first time

Meta has built custom computer chips to help with its artificial intelligence and video-processing tasks and is talking about them in public for the first time. The social ...

CNBC

Atmospheric Oxygen-only Plasma for Decapsulation of Advanced Packages

Work presented in this paper demonstrates how artifact-free Microwave Induced Plasma (MIP) decapsulation enables true root cause failure analysis of packaged ICs.

Technical Paper

At the vanguard of India's semiconductor ambition: a conversation with Foxconn-Vedanta JV CEO

India is putting all its weight behind efforts to manufacture semiconductors locally. At the forefront of this is the joint venture between Foxconn and Vedanta. Speaking ...

Digitimes

Technical Papers

- Improving SiC Power Devices with Laser Ohmic Contact Formation
- Defluxing of Copper Pillar Bumped Flip-Chips
- Functional testing of 0.3mm pitch WLP
- Vacuum Fluxless Reflow Technology for Fine Pitch Interconnect Bumping Applications
- Master Advanced Packaging Inspection
- Optimized Reflow Solder TIMs Processes for Heterogeneous Packages
- Packaging Solutions for Unique Markets

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Test Your Knowledge
Who is known as The Father of Geometry?
See answer below.

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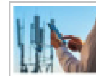
QP Technologies

Press Releases

EV Group Solutions for Heterogeneous Integration to be Highlighted at ECTC 2023
EV Group (EVG) announced that new developments in heterogeneous integration enabled by its advanced wafer-to-wafer (W2W) and die-to-wafer (D2W) bonding, lithography ...
EV Group

Accelerating automotive transformation: the power of semiconductor sensors
Sensing techniques continue to proliferate. Initially meant to optimize the powertrain's efficiency, growing safety concerns have made some sensors mandatory: ABS, ESC, airbags, ...
YOLE Group

EC-1031M-2 Easy To Use, Versatile Potting Compound
epoxySet produces the EC-1031M-2, a 1:1 mix, epoxy potting compound designed for potting and encapsulating electronics as well as motors, coils, transformers, pumps, amplifiers ...
EpoxySet Inc.

Do thin wafers have you frazzled?

Our new ADJUST-A-VAC allows you to reduce the vacuum pressure from just below atmospheric pressure to up to ten inches of mercury. A LED bar display shows the vacuum level.
Virtual Industries, Inc.

Touch Free BGA Solder Ball Removal

Watch a video that shows touch-free BGA component deballing. This precision process is highly reliable when preparing BGA components prior to reballing.
Circuit Technology Center

Pushing the Limits: Testing Higher-Power Next-Gen Semiconductors
The ever-evolving landscape of technology requires increasingly higher-power semiconductors, presenting a host of challenges for engineers in the field. With the ...
EE Times

China bans Micron chips for 'severe cybersecurity risks', drawing rebuke from Washington as tech war revs up
China banned the sale of Micron Technology's products on Sunday, claiming that the US memory chip company posed a "national security risk", an assertion the US ...
South China Morning Post

Memory chip market may be showing signs of bottoming out as China's YMTC leads Samsung, Micron in raising prices
The memory chip market may have started to bottom out after more than a year of price declines brought about by a supply glut, as Yangtze Memory Technologies ...
South China Morning Post

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Week In Review: Semiconductor Manufacturing, Test
TECHCET is forecasting semiconductor precursor revenues, both for high-ϰ metal dielectrics and low-ϰ dielectrics, will increase in the second half of 2023, rebounding ...
Semiconductor Engineering

Managing Yield With EUV Lithography And Stochastics
Identifying issues that actually affect yield is becoming more critical and more difficult at advanced nodes, but there is progress. Although they are closely related, ...
Semiconductor Engineering

Britain launches $1.2 billion semiconductor plan after U.S. and EU splurge on chips
The U.K. announced up to £1 billion ($1.24 billion) of support for its semiconductor industry, seeking to boost its domestic chipmaking capabilities and prevent further ...
CNBC

Semiconductor Manufacturing Monitor Points to Moderating Industry Contraction in Q2 2023
The current global semiconductor manufacturing industry contraction is expected to moderate in the second quarter of 2023 and give way to a gradual recovery starting in the third ...
SEMI

Precision Wire bonding Solutions

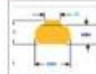
Achieve excellent wire bonding results with our advanced equipment and skilled technicians. Trust us for precise and reliable semiconductor assembly.
Golden Altos Corporation

Quote of the Day
It is a common experience that a problem difficult at night is resolved in the morning after the committee of sleep has worked on it.
John Steinbeck

UL Certified Epoxy Resists Arcing

Master Bond EP21AC is a two part epoxy with a non-halogenated filler for applications where arc resistance and flame retardancy are required.
Master Bond

Gold Planar Bumps for Flip Chip Bonding with Challenging Applications



Achieving consistent, quality Au Planar bumps has been a challenge. This case study explore these difficult specifications and how to achieve them.
Palomar Technologies Inc.

What Year Was It?
Great Emigration Departs for Oregon

A massive wagon train, made up of 1,000 settlers and 1,000 head of cattle, sets off down the Oregon Trail from Independence, Missouri.
The day was May 22. What year was it?

New Solution for Thin Wafer Handling

Thermoplastic layer conformally coats device features. Curable layer

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CyberOptics by Nordson Test & Inspection

[**MEMS & Sensors Market Forecast: Impact Of Semiconductor Industry Slowdown**]
Of all technologies, MEMS and sensors stand out for their far-reaching promise to improve lives across segments such as Internet of Things (IoT), wearables, smart home, ...
Semiconductor Engineering

[**Micron Is Said to Get $1.5 Billion From Japan for Next-Gen Chips**]
Micron Technology Inc is poised to land about $1.5 billion in financial incentives from the Japanese government to help it make next-generation memory chips in the country ...
Taipei Times

[**TSMC to continue investing in Japan: company chairman**]
Taiwan Semiconductor Manufacturing Co (TSMC) will continue investing in Japan and strengthening cooperation with semiconductor partners in the country, chairman ...
Taipei Times

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Complex High Value Products
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Calendar

- May 22, 2023: Overview of semiconductor manufacturing/Malta, NY
- May 23, 2023: SEMICON Southeast Asia 2023
- May 23, 2023: MEMS & Sensors Technical Congress—MSTC 2023
- May 30, 2023: 2023 IEEE 73rd Electronic Components and Technology Conference

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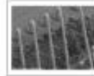
provides low-force bonding and conforms to thermoplastic layer. Enables device thinning ≤ 10 µm.
Brewer Science

Undisputable decapsulation

Artifact-free decapsulation of silver wire bonded packages using atmospheric pressure Microwave Induced Plasma (MIP). Fully automatic. 100% Reliable.
JIACO Instruments

Cartoon of the Day

"If my math is correct, we only gained 0.000976521 pounds per second on our cruise."

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Better Bonds, with Atmospheric Plasma

Our Atmospheric Plasma systems prepare surfaces for direct bonding, remove residue, and prepare surfaces for adhesion. Click Here to learn more.
Ontos Equipment Systems

Test Your Knowledge Answer
Who is known as The Father of Geometry?
Answer: Euclid of Alexandria is called the Father of Geometry. He received his education at Plato's Academy in Greece and moved to Egypt to teach. He taught during the reign of Ptolemy I Soter, the first Macedonian ruler.

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